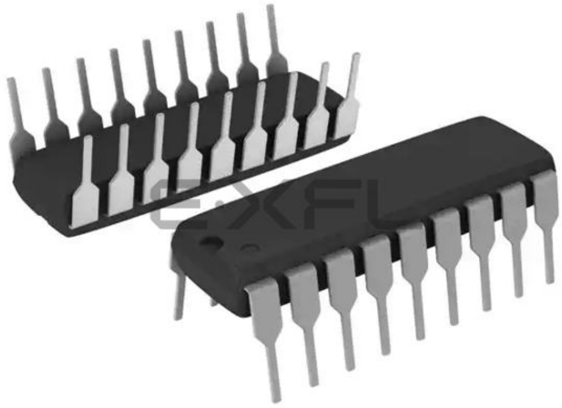
Microchip Technology - PIC16C56-RC/P Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c56-rc-p

4.3 External Crystal Oscillator Circuit

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 4-3 shows an implementation example of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 4-3: EXAMPLE OF EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)

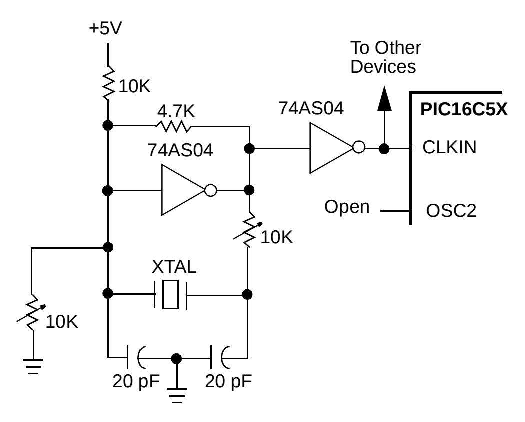
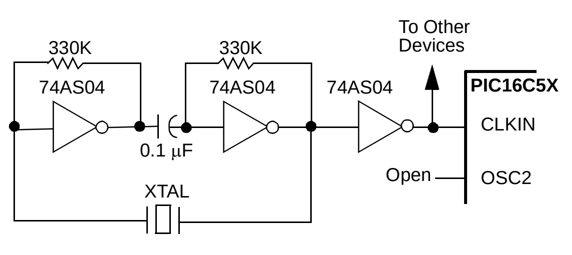


Figure 4-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 4-4: EXAMPLE OF EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)



NOTES:

5.1 Power-On Reset (POR)

The PIC16C5X family incorporates on-chip Power-On Reset (POR) circuitry which provides an internal chip RESET for most power-up situations. To use this feature, the user merely ties the MCLR/VPP pin to VDD. A simplified block diagram of the on-chip Power-On Reset circuit is shown in Figure 5-1.

The Power-On Reset circuit and the Device Reset Timer (Section 5.2) circuit are closely related. On power-up, the RESET latch is set and the DRT is RESET. The DRT timer begins counting once it detects MCLR to be high. After the time-out period, which is typically 18 ms, it will RESET the reset latch and thus end the on-chip RESET signal.

A power-up example where MCLR is not tied to VDD is shown in Figure 5-3. VDD is allowed to rise and stabilize before bringing MCLR high. The chip will actually come out of reset TDRT msec after MCLR goes high.

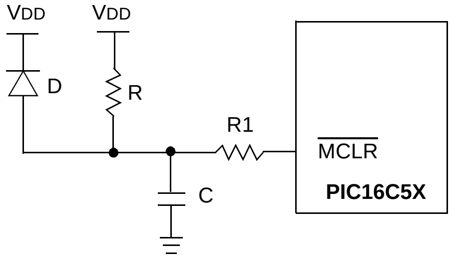
In Figure 5-4, the on-chip Power-On Reset feature is being used (MCLR and VDD are tied together). The VDD is stable before the start-up timer times out and there is no problem in getting a proper RESET. However, Figure 5-5 depicts a problem situation where VDD rises too slowly. The time between when the DRT senses a high on the MCLR/VPP pin, and when the MCLR/VPP pin (and VDD) actually reach their full value, is too long. In this situation, when the start-up timer times out, VDD has not reached the VDD (min) value and the chip is, therefore, not guaranteed to function correctly. For such situations, we recommend that external RC circuits be used to achieve longer POR delay times (Figure 5-2).

Note:	When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

For more information on PIC16C5X POR, see *Power-Up Considerations* - AN522 in the Embedded Control Handbook.

The POR circuit does not produce an internal RESET when VDD declines.

FIGURE 5-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- External Power-On Reset circuit is required only if VDD power-up is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
- R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device electrical specification.
- R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

NOTES:

7.6 I/O Programming Considerations

7.6.1 BI-DIRECTIONAL I/O PORTS

Some instructions operate internally as read followed by write operations. The `BCF` and `BSF` instructions, for example, read the entire port into the CPU, execute the bit operation and re-write the result. Caution must be used when these instructions are applied to a port where one or more pins are used as input/outputs. For example, a `BSF` operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU, bit5 to be set and the PORTB value to be written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (say bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit0 is switched into Output mode later on, the content of the data latch may now be unknown.

Example 7-1 shows the effect of two sequential read-modify-write instructions (e.g., `BCF, BSF`, etc.) on an I/O port.

A pin actively outputting a high or a low should not be driven from external devices at the same time in order to change the level on this pin (“wired-or”, “wired-and”). The resulting high output currents may damage the chip.

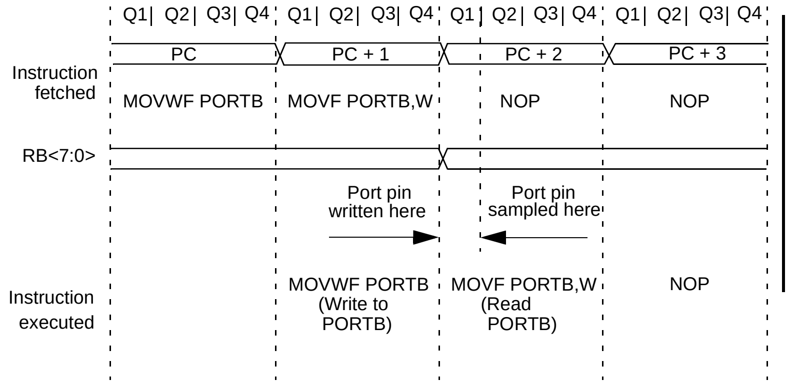
EXAMPLE 7-1: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
;Initial PORT Settings
; PORTB<7:4> Inputs
; PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry
;
;                   PORT latch  PORT pins
;                   ----------  ----------
  BCF   PORTB, 7   ;01pp pppp   11pp pppp
  BCF   PORTB, 6   ;10pp pppp   11pp pppp
  MOVLW H'3F'       ;
  TRIS  PORTB      ;10pp pppp   10pp pppp
;
;Note that the user may have expected the pin
;values to be 00pp pppp. The 2nd BCF caused
;RB7 to be latched as the pin value (High).
```

7.6.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 7-2). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction, which causes that file to be read into the CPU, is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a `NOP` or another instruction not accessing this I/O port.

FIGURE 7-2: SUCCESSIVE I/O OPERATION



This example shows a write to PORTB followed by a read from PORTB.

REGISTER 9-2: CONFIGURATION WORD FOR PIC16C54/C55/C56/C57

—	—	—	—	—	—	—	—	CP	WDTE	FOSC1	FOSC0
bit 11											bit 0

bit 11-4: **Unimplemented**: Read as ‘0’

bit 3: **CP:** Code protection bit.
`1` = Code protection off
`0` = Code protection on

bit 2: **WDTE:** Watchdog timer enable bit
`1` = WDT enabled
`0` = WDT disabled

bit 1-0: **FOSC1:FOSC0:** Oscillator selection bits(2)
`00` = LP oscillator
`01` = XT oscillator
`10` = HS oscillator
`11` = RC oscillator

Note 1: Refer to the PIC16C5X Programming Specifications (Literature Number DS30190) to determine how to access the configuration word.
2: PIC16LV54A supports XT, RC and LP oscillator only.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

TABLE 10-2: INSTRUCTION SET SUMMARY

Mnemonic, Operands		Description	Cycles	12-Bit Opcode	Status Affected	Notes
				MSb LSb		
ADDWF	f,d	Add W and f	1	`0001 11df ffff`	C,DC,Z	1,2,4
ANDWF	f,d	AND W with f	1	`0001 01df ffff`	Z	2,4
CLRF	f	Clear f	1	`0000 011f ffff`	Z	4
CLRW	–	Clear W	1	`0000 0100 0000`	Z	
COMF	f, d	Complement f	1	`0010 01df ffff`	Z	
DECF	f, d	Decrement f	1	`0000 11df ffff`	Z	2,4
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	`0010 11df ffff`	None	2,4
INCF	f, d	Increment f	1	`0010 10df ffff`	Z	2,4
INCFSZ	f, d	Increment f, Skip if 0	1(2)	`0011 11df ffff`	None	2,4
IORWF	f, d	Inclusive OR W with f	1	`0001 00df ffff`	Z	2,4
MOVF	f, d	Move f	1	`0010 00df ffff`	Z	2,4
MOVWF	f	Move W to f	1	`0000 001f ffff`	None	1,4
NOP	–	No Operation	1	`0000 0000 0000`	None	
RLF	f, d	Rotate left f through Carry	1	`0011 01df ffff`	C	2,4
RRF	f, d	Rotate right f through Carry	1	`0011 00df ffff`	C	2,4
SUBWF	f, d	Subtract W from f	1	`0000 10df ffff`	C,DC,Z	1,2,4
SWAPF	f, d	Swap f	1	`0011 10df ffff`	None	2,4
XORWF	f, d	Exclusive OR W with f	1	`0001 10df ffff`	Z	2,4
BIT-ORIENTED FILE REGISTER OPERATIONS						
BCF	f, b	Bit Clear f	1	`0100 bbbf ffff`	None	2,4
BSF	f, b	Bit Set f	1	`0101 bbbf ffff`	None	2,4
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	`0110 bbbf ffff`	None	
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	`0111 bbbf ffff`	None	
LITERAL AND CONTROL OPERATIONS						
ANDLW	k	AND literal with W	1	`1110 kkkk kkkk`	Z	
CALL	k	Call subroutine	2	`1001 kkkk kkkk`	None	1
CLRWDT	k	Clear Watchdog Timer	1	`0000 0000 0100`	$\overline{TO}$, $\overline{PD}$	
GOTO	k	Unconditional branch	2	`101k kkkk kkkk`	None	
IORLW	k	Inclusive OR Literal with W	1	`1101 kkkk kkkk`	Z	
MOVLW	k	Move Literal to W	1	`1100 kkkk kkkk`	None	
OPTION	k	Load OPTION register	1	`0000 0000 0010`	None	
RETLW	k	Return, place Literal in W	2	`1000 kkkk kkkk`	None	
SLEEP	–	Go into standby mode	1	`0000 0000 0011`	$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register	1	`0000 0000 0fff`	None	3
XORLW	k	Exclusive OR Literal to W	1	`1111 kkkk kkkk`	Z	

Note 1: The 9th bit of the program counter will be forced to a '0' by any instruction that writes to the PC except for `GOTO` (see Section 6.5 for more on program counter).

2: When an I/O register is modified as a function of itself (e.g. `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

3: The instruction `TRIS f`, where f = 5, 6 or 7 causes the contents of the W register to be written to the tristate latches of PORTA, B or C respectively. A '1' forces the pin to a hi-impedance state and disables the output buffers.

4: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared (if assigned to TMR0).

CALL Subroutine Call

Syntax: [*label*] CALL k

Operands: $0 \le k \le 255$

Operation: (PC) + 1→ TOS;
k → PC<7:0>;
(STATUS<6:5>) → PC<10:9>;
0 → PC<8>

Status Affected: None

Encoding:

`1001`	`kkkk`	`kkkk`

Description: Subroutine call. First, return address (PC+1) is pushed onto the stack. The eight bit immediate address is loaded into PC bits <7:0>. The upper bits PC<10:9> are loaded from STATUS<6:5>, PC<8> is cleared. `CALL` is a two-cycle instruction.

Words: 1

Cycles: 2

Example: `HERE CALL THERE`

Before Instruction
PC = address `(HERE)`
After Instruction
PC = address `(THERE)`
TOS = address `(HERE + 1)`

CLRF Clear f

Syntax: [*label*] CLRF f

Operands: $0 \le f \le 31$

Operation: 00h → (f);
1 → Z

Status Affected: Z

Encoding:

`0000`	`011f`	`ffff`

Description: The contents of register 'f' are cleared and the Z bit is set.

Words: 1

Cycles: 1

Example: `CLRF FLAG_REG`

Before Instruction
FLAG_REG = 0x5A
After Instruction
FLAG_REG = 0x00
Z = 1

CLRW Clear W

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W);
1 → Z

Status Affected: Z

Encoding:

`0000`	`0100`	`0000`

Description: The W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Example: `CLRW`

Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT Clear Watchdog Timer

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT;
0 → WDT prescaler (if assigned);
1 → $\overline{\text{TO}}$;
1 → $\overline{\text{PD}}$

Status Affected: $\overline{\text{TO}}$, $\overline{\text{PD}}$

Encoding:

`0000`	`0000`	`0100`

Description: The `CLRWDT` instruction resets the WDT. It also resets the prescaler, if the prescaler is assigned to the WDT and not Timer0. Status bits $\overline{\text{TO}}$ and $\overline{\text{PD}}$ are set.

Words: 1

Cycles: 1

Example: `CLRWDT`

Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{\text{TO}}$ = 1
$\overline{\text{PD}}$ = 1

IORLW	**Inclusive OR literal with W**
Syntax:	[*label*] IORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .OR. (k) → (W)
Status Affected:	Z
Encoding:	`1101` `kkkk` `kkkk`
Description:	The contents of the W register are OR'ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	`IORLW 0x35`

Before Instruction
W = 0x9A
After Instruction
W = 0xBF
Z = 0

IORWF	**Inclusive OR W with f**
Syntax:	[*label*] IORWF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W).OR. (f) → (dest)
Status Affected:	Z
Encoding:	`0001` `00df` `ffff`
Description:	Inclusive OR the W register with register 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
Words:	1
Cycles:	1
Example:	`IORWF RESULT, 0`

Before Instruction
RESULT = 0x13
W = 0x91
After Instruction
RESULT = 0x13
W = 0x93
Z = 0

MOVF	**Move f**
Syntax:	[*label*] MOVF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(f) → (dest)
Status Affected:	Z
Encoding:	`0010` `00df` `ffff`
Description:	The contents of register 'f' is moved to destination 'd'. If 'd' is 0, destination is the W register. If 'd' is 1, the destination is file register 'f'. 'd' is 1 is useful to test a file register since status flag Z is affected.
Words:	1
Cycles:	1
Example:	`MOVF FSR, 0`

After Instruction
W = value in FSR register

MOVLW	**Move Literal to W**
Syntax:	[*label*] MOVLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W)
Status Affected:	None
Encoding:	`1100` `kkkk` `kkkk`
Description:	The eight bit literal 'k' is loaded into the W register.
Words:	1
Cycles:	1
Example:	`MOVLW 0x5A`

After Instruction
W = 0x5A

12.4 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial) PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	VSS	—	0.2 VDD	V	Pin at hi-impedance
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	VSS	—	0.15 VDD	V	PIC16C5X-RC only(3)
		OSC1 (Schmitt Trigger)	VSS	—	0.3 VDD	V	PIC16C5X-XT, 10, HS, LP
D040	VIH	**Input High Voltage**					
		I/O ports	0.45 VDD	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		I/O ports	0.36 VDD	—	VDD	V	VDD > 5.5V
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	PIC16C5X-RC only(3)
		OSC1 (Schmitt Trigger)	0.7 VDD	—	VDD	V	PIC16C5X-XT, 10, HS, LP
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	–1	0.5	+1	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	–5	—	—	μA	VPIN = VSS + 0.25V
		MCLR	—	0.5	+5	μA	VPIN = VDD
		T0CKI	–3	0.5	+3	μA	VSS ≤ VPIN ≤ VDD
		OSC1	–3	0.5	+3	μA	VSS ≤ VPIN ≤ VDD, PIC16C5X-XT, 10, HS, LP
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, PIC16C5X-RC
D090	VOH	**Output High Voltage(2)**					
		I/O ports	VDD – 0.7	—	—	V	IOH = –5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD – 0.7	—	—	V	IOH = –1.0 mA, VDD = 4.5V, PIC16C5X-RC

* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the $\overline{\text{MCLR}}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

AC Characteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –40°C ≤ TA ≤ +125°C for extended						
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
1	TOSC	External CLKIN Period[(1)]	250	—	—	ns	XT OSC mode
			100	—	—	ns	10 MHz mode
			50	—	—	ns	HS OSC mode (Comm/Ind)
			62.5	—	—	ns	HS OSC mode (Ext)
			25	—	—	μs	LP OSC mode
		Oscillator Period[(1)]	250	—	—	ns	RC OSC mode
			250	—	10,000	ns	XT OSC mode
			100	—	250	ns	10 MHz mode
			50	—	250	ns	HS OSC mode (Comm/Ind)
			62.5	—	250	ns	HS OSC mode (Ext)
			25	—	—	μs	LP OSC mode
2	Tcy	Instruction Cycle Time[(2)]	—	4/FOSC	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	85*	—	—	ns	XT oscillator
			20*	—	—	ns	HS oscillator
			2.0*	—	—	μs	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	25*	ns	HS oscillator
			—	—	50*	ns	LP oscillator

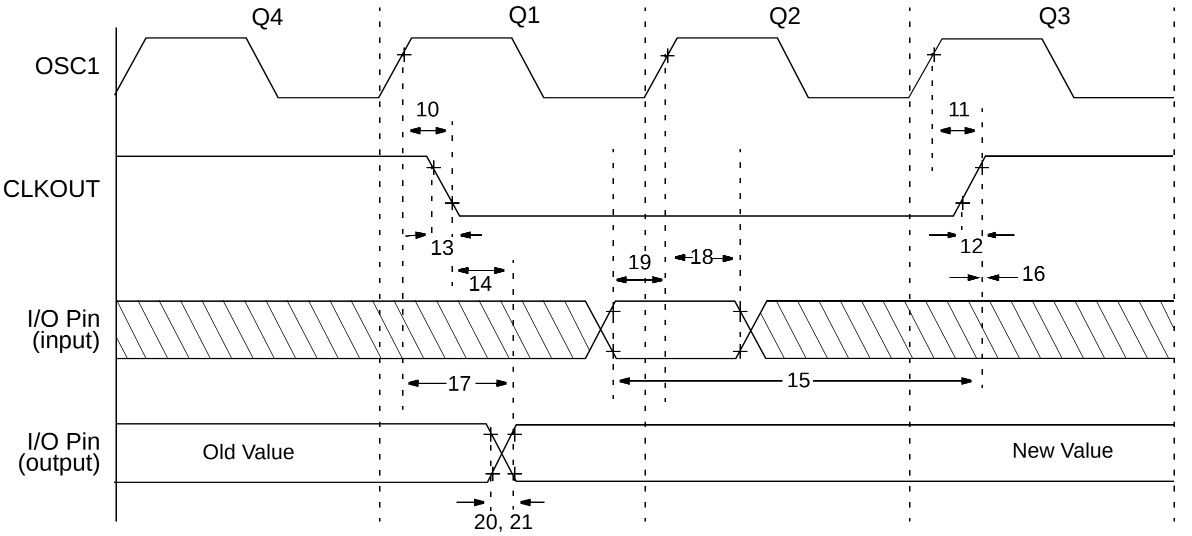
* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.
When an external clock input is used, the “max” cycle time limit is “DC” (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

FIGURE 13-3: CLKOUT AND I/O TIMING - PIC16CR54A



Note: Please refer to Figure 13.1 for load conditions.

TABLE 13-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16CR54A

AC Characteristics	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ T_A ≤ +70°C for commercial –40°C ≤ T_A ≤ +85°C for industrial –40°C ≤ T_A ≤ +125°C for extended					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**
10	TosH2ckL	OSC1↑ to CLKOUT↓(1)	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑(1)	—	15	30**	ns
12	TckR	CLKOUT rise time(1)	—	5.0	15**	ns
13	TckF	CLKOUT fall time(1)	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑(1)	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑(1)	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid(2)	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time(2)	—	10	25**	ns
21	TioF	Port output fall time(2)	—	10	25**	ns

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

2: Please refer to Figure 13.1 for load conditions.

FIGURE 14-21: PORTA, B AND C IOL vs. VOL, VDD = 3 V

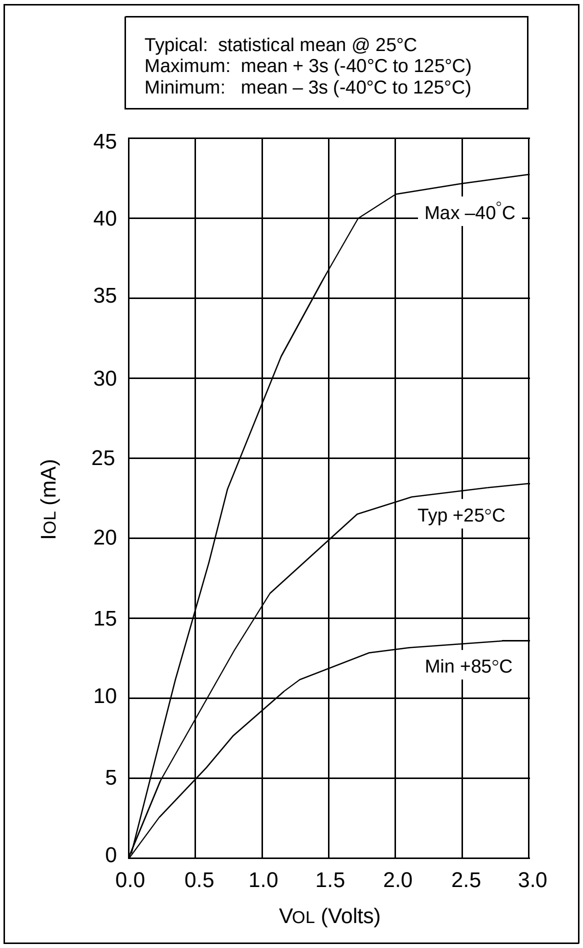
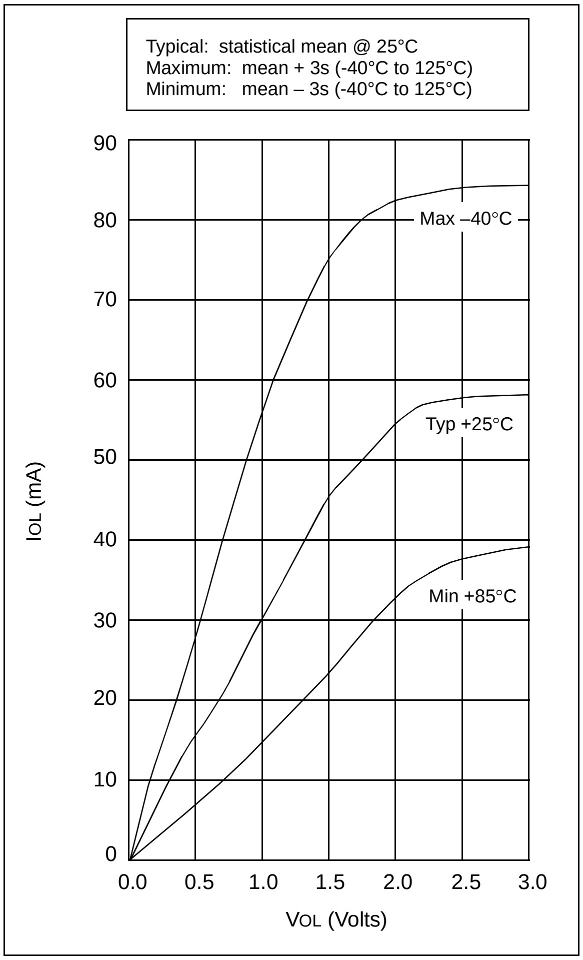


FIGURE 14-22: PORTA, B AND C IOL vs. VOL, VDD = 5 V



15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial) PIC16C54A-04I, 10I, 20I (Industrial) PIC16LC54A-04 (Commercial) PIC16LC54A-04I (Industrial)

PIC16LC54A-04 **PIC16LC54A-04I** (Commercial, Industrial)	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ T_A ≤ +70°C for commercial –40°C ≤ T_A ≤ +85°C for industrial
PIC16C54A-04, 10, 20 **PIC16C54A-04I, 10I, 20I** (Commercial, Industrial)	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ T_A ≤ +70°C for commercial –40°C ≤ T_A ≤ +85°C for industrial

Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D001	VDD	**Supply Voltage**					
		PIC16LC54A	3.0	—	6.25	V	XT and RC modes
			2.5	—	6.25	V	LP mode
D001A		PIC16C54A	3.0	—	6.25	V	RC, XT and LP modes
			4.5	—	5.5	V	HS mode
D002	VDR	**RAM Data Retention Voltage**(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D005	IDD	**Supply Current**(2)					
		PIC16LC5X	—	0.5	2.5	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Commercial
			—	11	35	µA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Industrial
D005A		PIC16C5X	—	1.8	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	2.4	8.0	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode
			—	4.5	16	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode
			—	14	29	µA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Commercial
			—	17	37	µA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in “Typ” column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended
PIC16C54A-04E, 10E, 20E (Extended)	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended

Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	**Supply Voltage**					
		PIC16LC54A	3.0 2.5	— —	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.5 4.5	— —	5.5 5.5	V V	RC and XT modes HS mode
D002	VDR	**RAM Data Retention Voltage**(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	**Supply Current**(2)					
		PIC16LC54A	—	0.5	25	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	11	35	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
			—	11	37	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Extended
D010A		PIC16C54A	—	1.8	3.3	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode
			—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

TABLE 15-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54A

AC Characteristics

Standard Operating Conditions (unless otherwise specified)
Operating Temperature 0°C ≤ TA ≤ +70°C for commercial
–40°C ≤ TA ≤ +85°C for industrial
–20°C ≤ TA ≤ +85°C for industrial - PIC16LV54A-02I
–40°C ≤ TA ≤ +125°C for extended

Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
1	TOSC	External CLKIN Period[(1)]	250	—	—	ns	XT OSC mode
			500	—	—	ns	XT OSC mode (PIC16LV54A)
			250	—	—	ns	HS OSC mode (04)
			100	—	—	ns	HS OSC mode (10)
			50	—	—	ns	HS OSC mode (20)
			5.0	—	—	μs	LP OSC mode
		Oscillator Period[(1)]	250	—	—	ns	RC OSC mode
			500	—	—	ns	RC OSC mode (PIC16LV54A)
			250	—	10,000	ns	XT OSC mode
			500	—	—	ns	XT OSC mode (PIC16LV54A)
			250	—	250	ns	HS OSC mode (04)
			100	—	250	ns	HS OSC mode (10)
			50	—	250	ns	HS OSC mode (20)
			5.0	—	200	μs	LP OSC mode
2	Tcy	Instruction Cycle Time[(2)]	—	4/FOSC	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	85*	—	—	ns	XT oscillator
			20*	—	—	ns	HS oscillator
			2.0*	—	—	μs	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	25*	ns	HS oscillator
			—	—	50*	ns	LP oscillator

* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.
When an external clock input is used, the “max” cycle time limit is “DC” (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

FIGURE 16-18: TRANSCONDUCTANCE (gm) OF LP OSCILLATOR vs. VDD

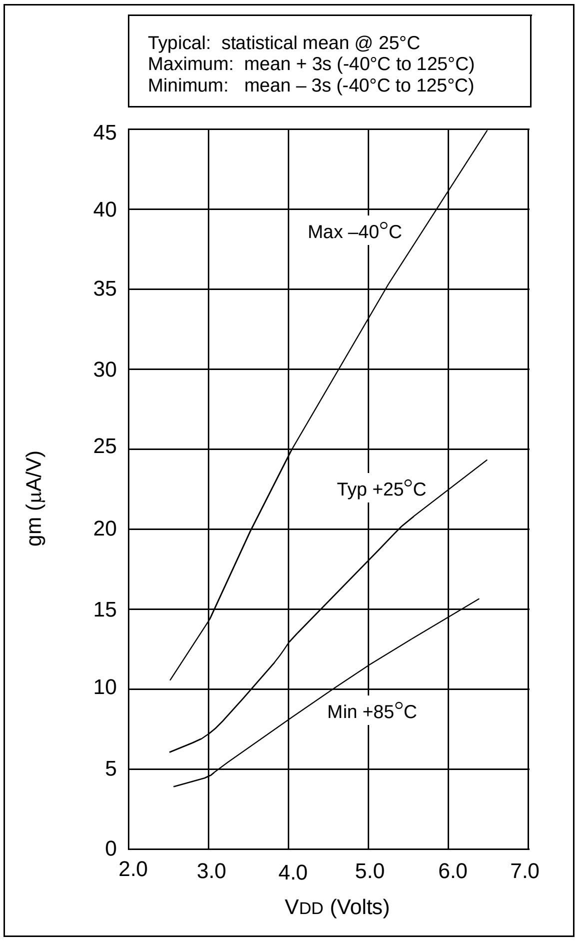


FIGURE 16-19: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD

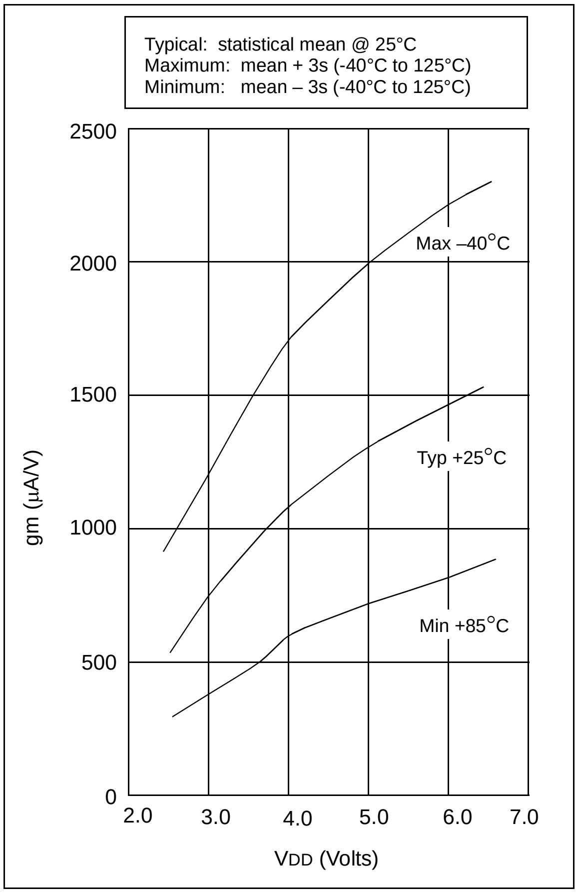


FIGURE 18-8: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF I/O PINS vs. VDD

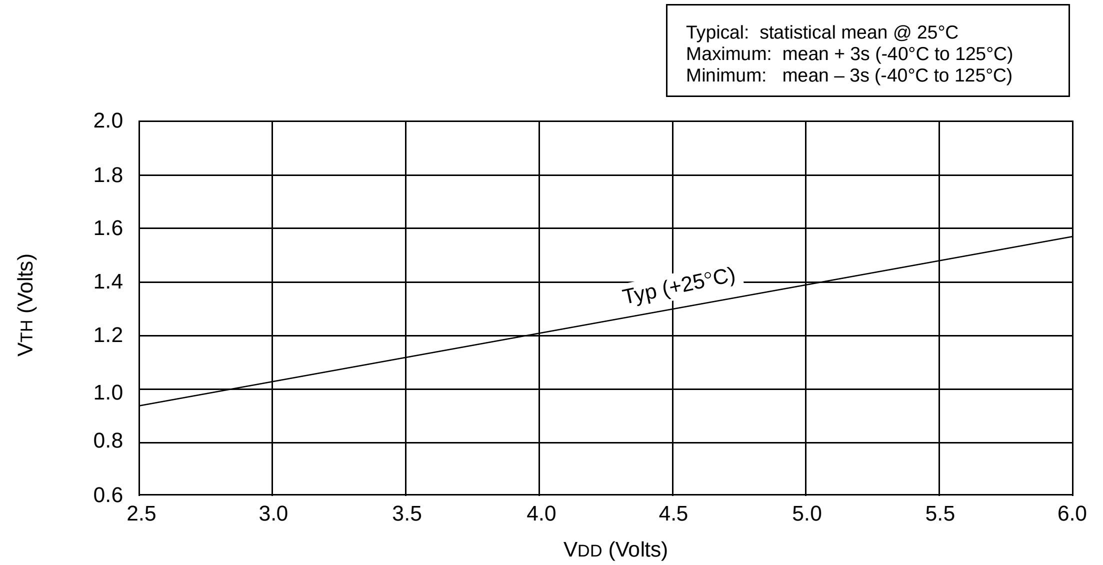
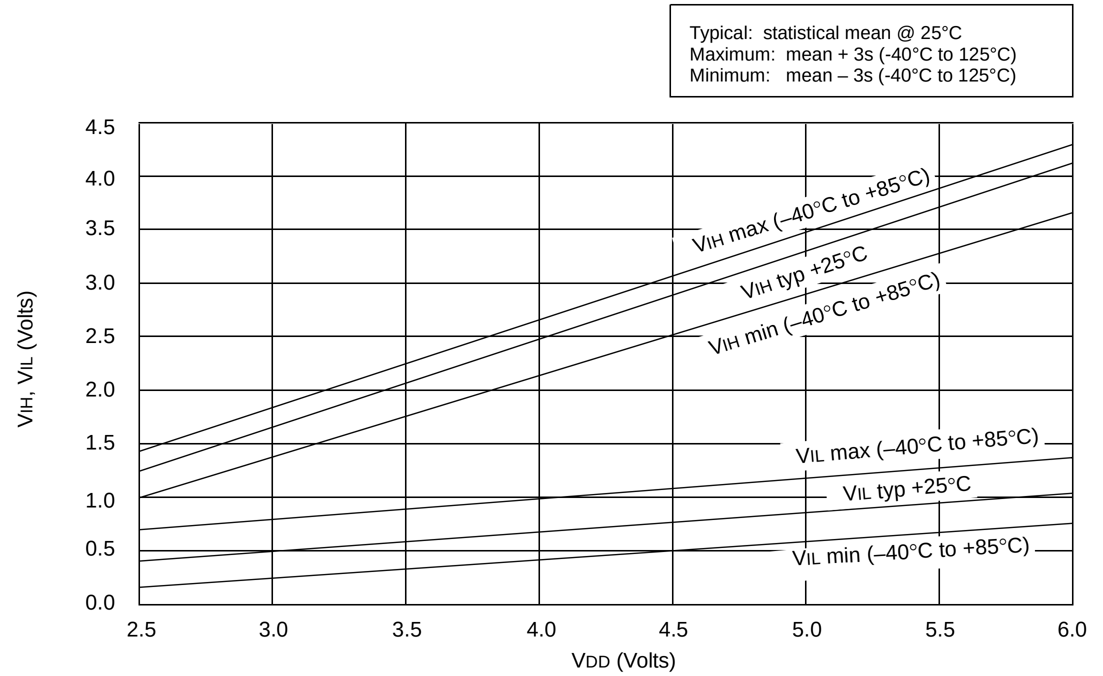


FIGURE 18-9: VIH, VIL OF $\overline{\text{MCLR}}$, T0CKI AND OSC1 (IN RC MODE) vs. VDD



Note: These input pins have Schmitt Trigger input buffers.

19.1 DC Characteristics:PIC16C54C/C55A/C56A/C57C/C58B-40 (Commercial)(1)

PIC16C54C/C55A/C56A/C57C/C58B-40 (Commercial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	4.5	—	5.5	V	HS mode from 20 - 40 MHz
D002	VDR	**RAM Data Retention Voltage**(2)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	**Supply Current**(3)	— —	5.2 6.8	12.3 16	mA mA	FOSC = 40 MHz, VDD = 4.5V, HS mode FOSC = 40 MHz, VDD = 5.5V, HS mode
D020	IPD	**Power-down Current**(3)	— —	1.8 9.8	7.0 27*	μA μA	VDD = 5.5V, WDT disabled, Commercial VDD = 5.5V, WDT enabled, Commercial

* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: Device operation between 20 MHz to 40 MHz requires the following: VDD between 4.5V to 5.5V, OSC1 pin externally driven, OSC2 pin not connected, HS oscillator mode and commercial temperatures. For operation between DC and 20 MHz, See Section 19.1.

2: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

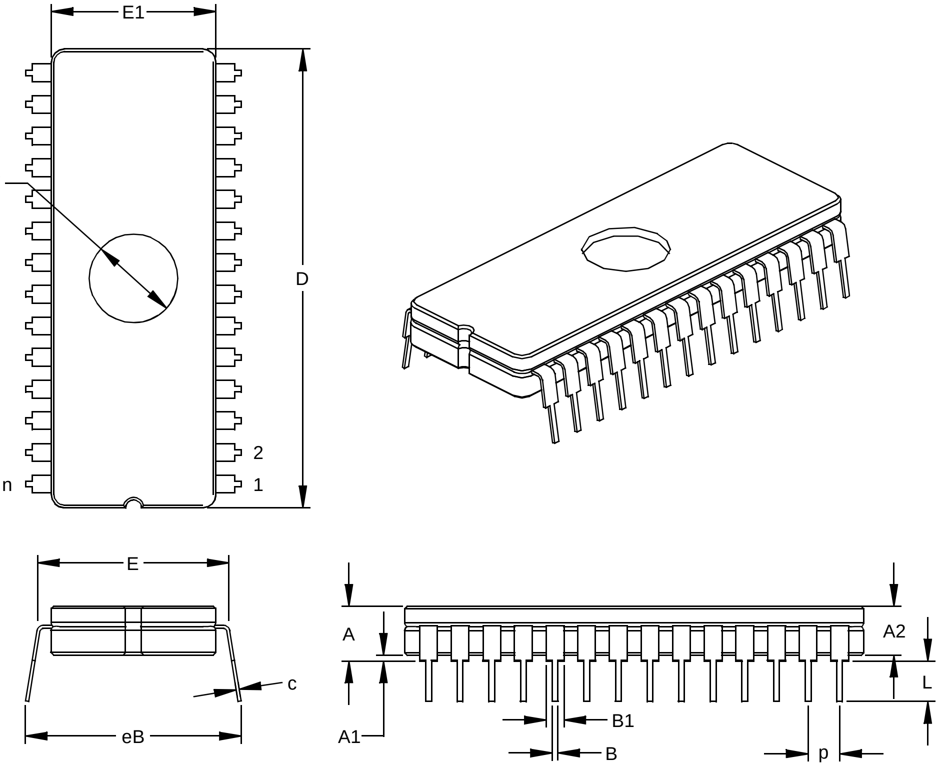
3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

28-Lead Ceramic Dual In-line with Window (JW) – 600 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES*			MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.195	.210	.225	4.95	5.33	5.72
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.038	.060	0.38	0.95	1.52
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Ceramic Pkg. Width	E1	.514	.520	.526	13.06	13.21	13.36
Overall Length	D	1.430	1.460	1.490	36.32	37.08	37.85
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.058	.065	1.27	1.46	1.65
Lower Lead Width	B	.016	.020	.023	0.41	0.51	0.58
Overall Row Spacing §	eB	.610	.660	.710	15.49	16.76	18.03
Window Diameter	W	.270	.280	.290	6.86	7.11	7.37

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-103
Drawing No. C04-013